

TMG60N10P

N-Channel Enhancement Mosfet

General Description

- Low $R_{DS(ON)}$
- RoHS and Halogen-Free Compliant

Applications

- Load switch
- PWM

General Features

$V_{DS} = 100V$ $I_D = 60A$

$R_{DS(ON)} = 13.8m\Omega (typ.) @ V_{GS} = 10V$

100% UIS Tested

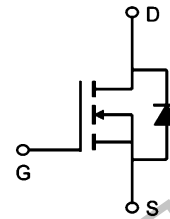
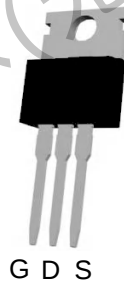
100% R_g Tested



P:TO-220AB



Marking: G60N10



Absolute Maximum Ratings ($T_c = 25^\circ C$ Unless Otherwise Noted)

Symbol	Parameter	Ratings	Units
V_{DS}	Drain-Source Voltage	100	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Continuous Drain Current ¹⁾ , $T_c = 25^\circ C$	60	A
$I_{D, pulse}$	Pulsed drain current ²⁾ , $T_c = 25^\circ C$	98	A
P_D	Power dissipation ³⁾ , $T_c = 25^\circ C$	96	W
E_{AS}	Single pulsed avalanche energy ⁵⁾	65	mJ
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55 to +150	$^\circ C$

Thermal Data

Symbol	Parameter	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction to Case	1.67	$^\circ C/W$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient ⁴⁾	62	

TMG60N10P

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Electrical Characteristics: ($T_C=25^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
Off Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250 μ A	100	---	---	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{GS} =0V, V _{DS} =100V	---	---	1	μ A
I _{GSS}	Gate-Source Leakage Current	V _{GS} = ± 20V, V _{DS} =0A	---	---	± 100	nA
On Characteristics						
V _{GS(th)}	GATE-Source Threshold Voltage	V _{GS} =V _{DS} , I _D =250 μ A	1.0	2.0	.0	V
R _{DS(ON)}	Drain-Source On Resistance	V _{GS} =10V, I _D =10A	---	13.8	20	m Ω
		V _{GS} =4.5V, I _D =7A	---	---	---	
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} =50V, V _{GS} =0V, f=100KHz	---	1000	---	pF
C _{OSS}	Output Capacitance		---	180	---	
C _{rss}	Reverse Transfer Capacitance		---	9.5	---	
Switching Characteristics						
t _{d(on)}	Turn-On Delay Time	V _{DS} =50V, I _D =5A, V _{GS} =10V, R _G =10Ω	---	16.6	--	ns
t _r	Rise Time		---	3.8	---	ns
t _{d(off)}	Turn-Off Delay Time		---	75.5	---	ns
t _f	Fall Time		---	46	---	ns
Q _g	Total Gate Charge	V _{GS} =10V, V _{DS} =50V, I _D =5A	---	16.2	---	nC
Q _{gs}	Gate-Source Charge		---	2.8	---	nC
Q _{gd}	Gate-Drain Charge		---	4.1	---	nC
V _{plateau}	Gate plateau voltage		---	3	---	V
Drain-Source Diode Characteristics						
V _{SD}	Source-Drain Diode Forward Voltage	V _{GS} =0V, I _S =12A	---	---	1.3	V
trr	Reverse Recovery Time	V _R =50 V, I _S =5 A, di/dt=100 A/ μ s	---	49	---	Ns
qrr	Reverse Recovery Charge		---	61.8	---	nc
I _{rmm}	Peak reverse recovery current		---	2.4	---	A

Notes:

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) P_d is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of $R_{\theta JA}$ is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with $T_a=25^{\circ}\text{C}$.
- 5) $V_{DD}=50V, V_{GS}=10V, L=0.3mH$, starting $T_j=25^{\circ}\text{C}$.

TMG60N10P

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Typical Characteristics

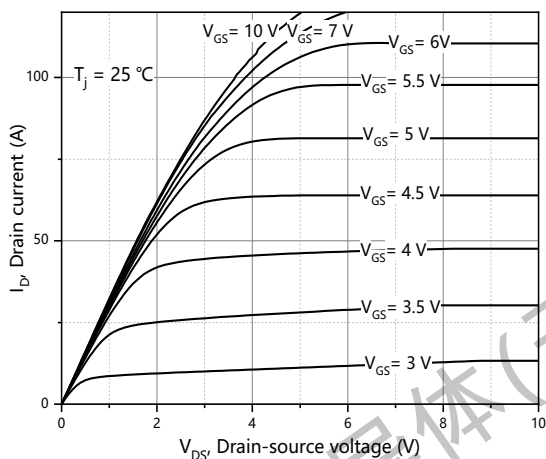


Figure 1. Typ. output characteristics

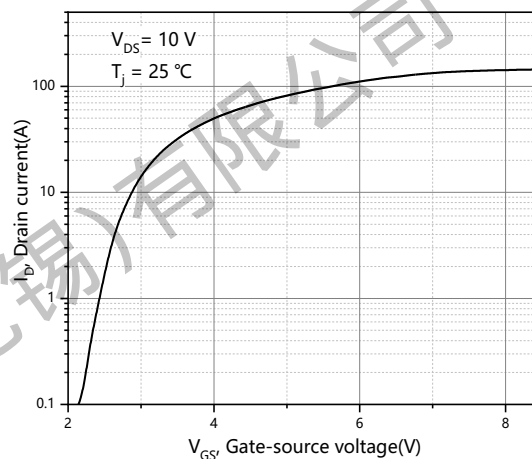


Figure 2. Typ. transfer characteristics

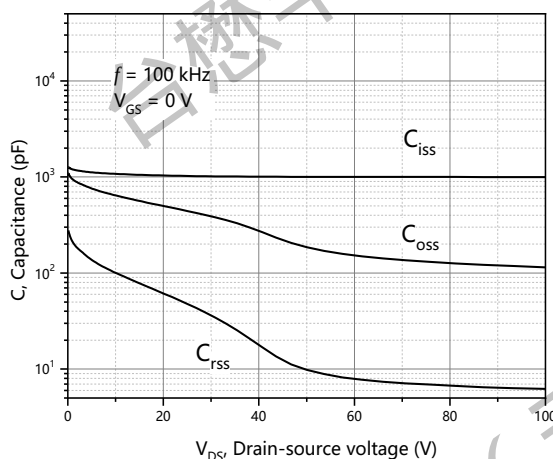


Figure 3. Typ. capacitances

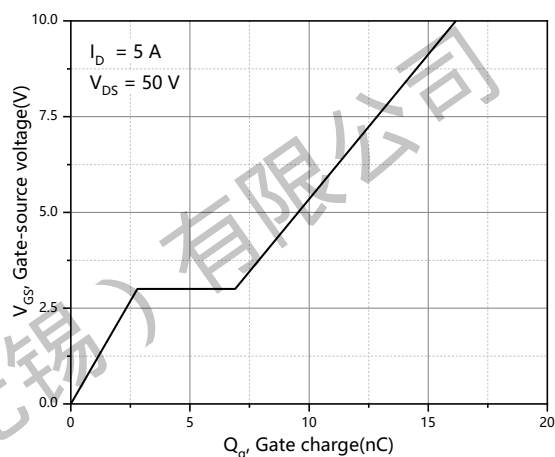


Figure 4. Typ. gate charge

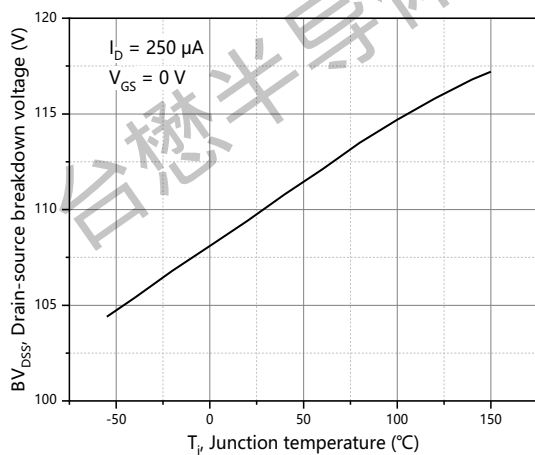


Figure 5. Drain-source breakdown voltage

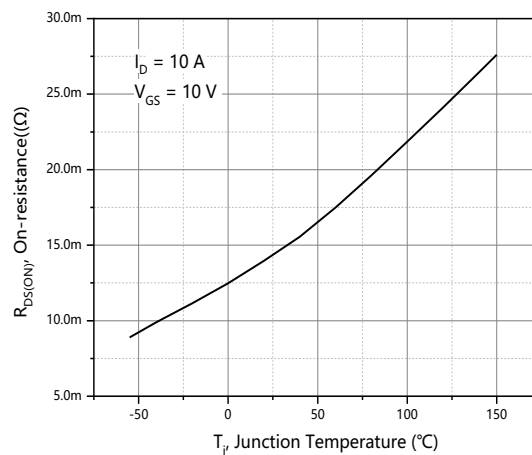


Figure 6. Drain-source on-state resistance

TMG60N10P

N-Channel Enhancement Mosfet

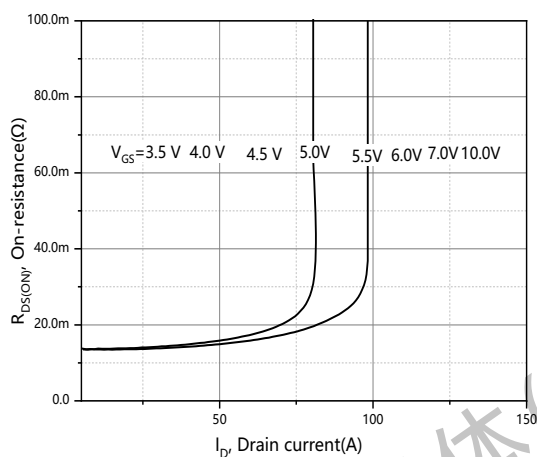


Figure 7. Drain-source on-state resistance

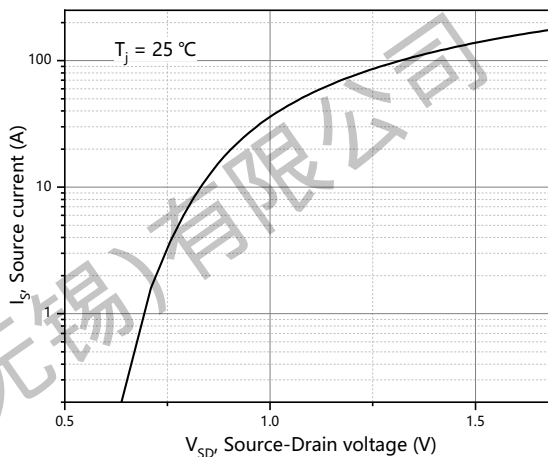


Figure 8. Forward characteristic of body diode

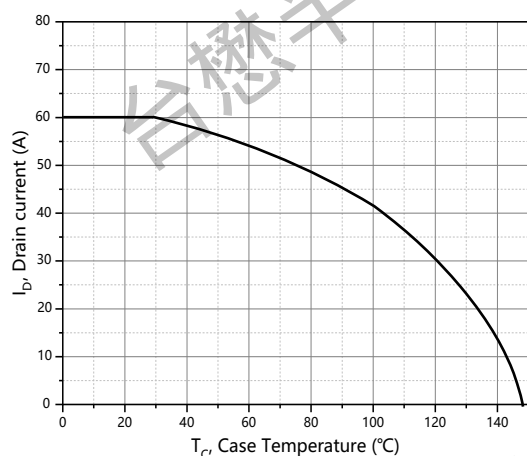


Figure 9. Drain current

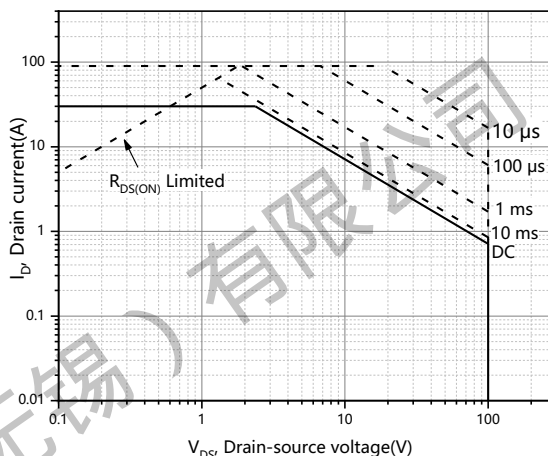


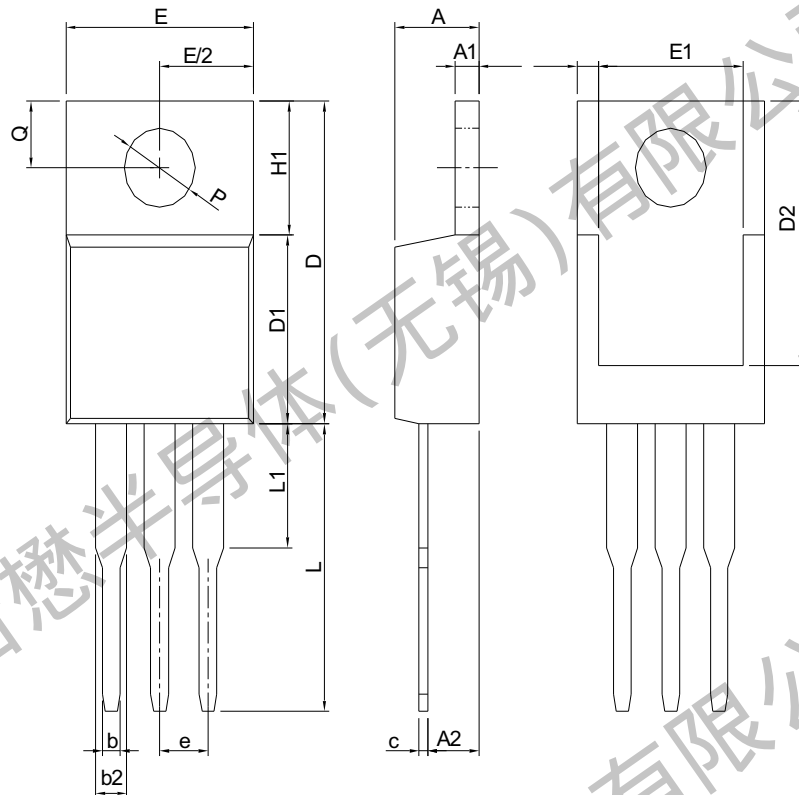
Figure 10. Safe operation area $T_C=25\text{ }^{\circ}\text{C}$



TMG60N10P

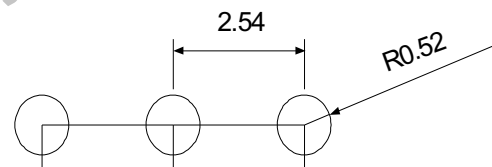
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Package Mechanical Data: TO-220AB



SYMBOL	TO-220			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	3.56	4.83	0.140	0.190
A1	0.51	1.40	0.020	0.055
A2	2.03	2.92	0.080	0.115
b	0.38	1.02	0.015	0.040
b2	1.14	1.78	0.045	0.070
c	0.36	0.61	0.014	0.024
D	14.22	16.51	0.560	0.650
D1	8.38	9.02	0.330	0.355
D2	12.19	13.65	0.480	0.537
E	9.65	10.67	0.380	0.420
E1	6.86	8.89	0.270	0.350
e	2.54 BSC		0.100 BSC	
H1	5.84	6.86	0.230	0.270
L	12.70	14.73	0.500	0.580
L1	-	6.35	-	0.250
P	3.53	4.09	0.139	0.161
Q	2.54	3.43	0.100	0.135

RECOMMENDED LAND PATTERN



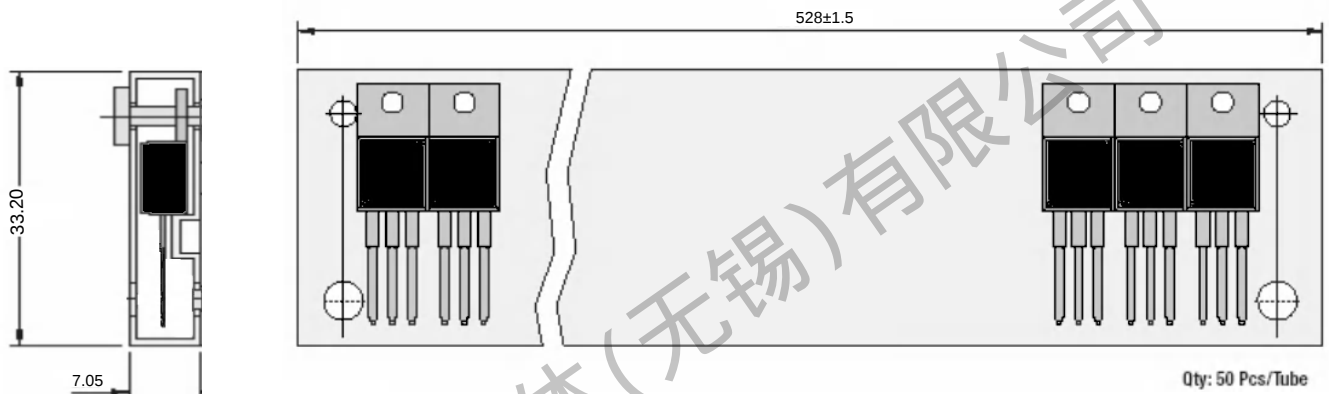
UNIT: mm

Note: Follow JEDEC TO-220 AB.



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All Dimensions are in mm

1.TO-220AB Packaging

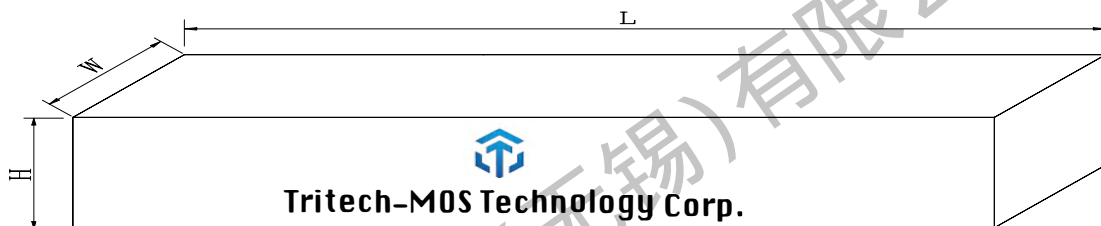
Package	Packing Form	Quantity		
		Tube	Inner Box [kpcs]	Outbox [kpcs]
TO-220AB	Tube Tape	50	5	1



TMG60N10P

N-Channel Enhancement Mosfet

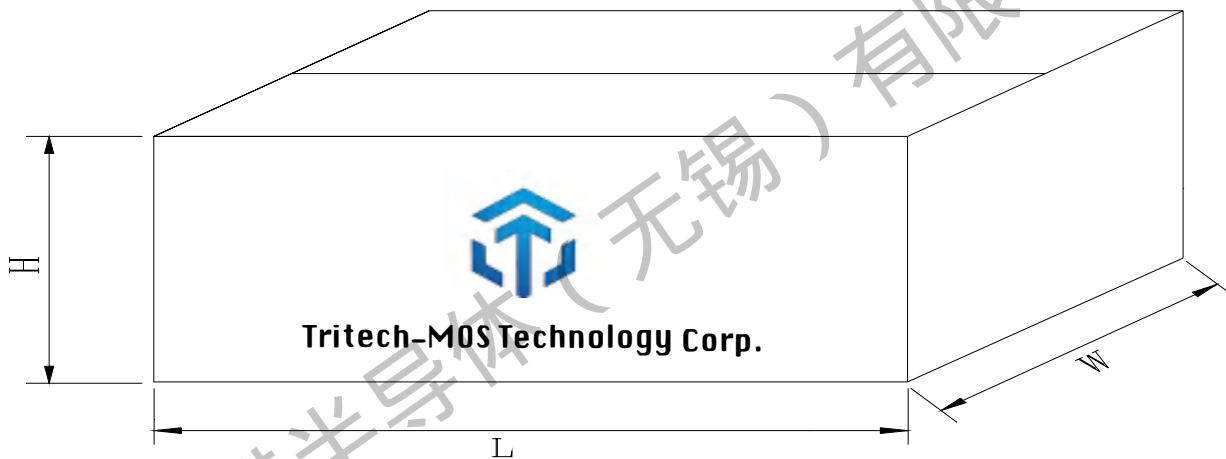
Inner Box



Dimension : 580 (L)×154(W) ×49(H) mm

Quantity : 50 ×20Ea = 1Kpcs

Outer Box



Dimension : 595(L)×285(W) ×185(H) mm

Quantity : 1K×5Ea = 5Kpcs

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Revision history:

Date	Rev	Description	Page
2023.06.27	23.06	Original	